

03-19-2002

B/O FORM PTO 1595 (1/31/92)
 Patent and Trademark Office
 RECORDATION FORM COVER SHEET
 PATENTS ONLY



102021980

HITA-0178

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of Conveying Party(ies):

(1) Yoichi TAMAKI, (2) Takayuki IWASAKI, (3) Kousuke TSUJI
 and (4) Chiyoshi KAMADA

Additional names of conveying parties attached

03/08/02

2. Name and Address of Receiving Party(ies):

(1) Name: Hitachi, Ltd.

Address: 6, Kanda Surugadai 4-chome
 Chiyoda-ku, Toyko, Japan

and

(2) Name: Hitachi ULSI Systems Co. Ltd

Address: 22-1 Josuihoncho 5-chome
 Kodaira-shi, Toyko, Japan

11002 U.S. PTO
 10/092594
 03/08/02

3. Nature of Conveyance:

- ☒ Assignment Merger
 Security Agreement Change of Name
 Other:

Execution Dates: (1)(4) February 12, 2002; (2)
 February 21, 2002; (3) February 14, 2002

4. (a) Patent Application Number(s):

If this document is being filed together with a new application,
 the execution dates of the application are:

: (1)(4) February 12, 2002; (2) February 21,
 2002; (3) February 14, 2002

Additional Numbers Attached.

4. (b) Patent Numbers:

5. Name and Address of Party to whom Correspondence Concerning this Document Should be Mailed:

Name: Stanley P. Fisher

Address: Reed Smith LLP
 3100 Fairview Park Dr.
 Suite 1400
 Falls Church, Va. 22042

6. Total Number of Applications and Patents Involved: 1

7. Total Fee: \$40.00
 (37 C.F.R. § 3.41)

- ☒ Enclosed.
☒ Authorized to be charged to deposit account.

8. Deposit Account Number: 08-1480

ATTACH DUPLICATE COPY OF THIS PAGE IF PAYING BY DEPOSIT ACCOUNT

DO NOT USE THIS SPACE

9. Statement and Signature:

To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.

March 8, 2002

Stanley P. Fisher, Registration No. 24, 344

Total number of pages comprising cover sheet: 1

JUAN CARLOS A. MARQUEZ
 Registration No. 34,072

03/14/2002 VTRU06G1 00000016 10092594

03 FC:581

40.00 00

ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD. and Hitachi ULSI Systems Co., Ltd., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 22-1, Josuihoncho 5-chome, Kodaira-shi, Tokyo, Japan, respectively, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD. and Hitachi ULSI Systems Co., Ltd., their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD. and Hitachi ULSI Systems Co., Ltd., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD. and Hitachi ULSI Systems Co., Ltd.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1) <u>Yoichi Tamaki</u> (Yoichi TAMAKI)	<u>12 / February / 2002</u>
2) <u>Takayuki Iwasaki</u> (Takayuki IWASAKI)	<u>21 / February / 2002</u>
3) <u>Kousuke Tsuji</u> (Kousuke TSUJI)	<u>14 / February / 2002</u>
4) <u>Chiyoshi Kamada</u> (Chiyoshi KAMADA)	<u>12 / February / 2002</u>
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____